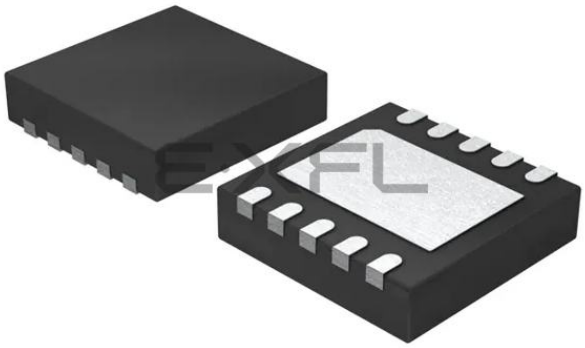

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	6
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.25V
Data Converters	A/D 6x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	10-VFDFN Exposed Pad
Supplier Device Package	10-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f524-c-im

Table 2.8. Reset Electrical Characteristics
–40 to +125 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
$\overline{RST}$ Output Low Voltage	I_{OL} = 8.5 mA, V_{DD} = 2.1 V	—	—	0.8	V
$\overline{RST}$ Input High Voltage		0.7 x V_{REGIN}	—	—	V
$\overline{RST}$ Input Low Voltage		—	—	0.3 x V_{REGIN}	V
$\overline{RST}$ Input Pullup Impedance	V_{REGIN} = 1.8 V V_{REGIN} = 2.7 V V_{REGIN} = 3.3 V V_{REGIN} = 5 V	— — — —	330 160 130 80	— — — —	kΩ kΩ kΩ kΩ
Missing Clock Detector Timeout	Time from last system clock rising edge to reset initiation	100	350	650	µs
Reset Time Delay ($T_{PORDelay}$)[1]	Delay between release of any reset source and code execution at location 0x0000	—	—	350	µs
Minimum $\overline{RST}$ Low Time to Generate a System Reset		10	—	—	µs
V_{DD} Monitor (VDDMON0)					
Low Threshold ($V_{RST-LOW}$)[1,2,3]	C8051F52x/53x C8051F52xA/53xA C8051F52x-C/53x-C	1.8 1.65 1.65	1.9 1.75 1.75	2.0 1.8 1.8	V V V
High Threshold ($V_{RST-HIGH}$)[3]	C8051F52x/53x C8051F52xA/53xA C8051F52x-C/53x-C	2.1 2.25 2.25	2.2 2.3 2.3	2.3 2.4 2.45	V V V
Turn-on Time		—	83	—	µs
Supply Current	V_{DD} = 2.1 V	—	1	2	µA
Level-Sensitive V_{DD} Monitor (VDDMON1)[1]					
Threshold (V_{RST1})[1,2,3]	C8051F52x-C/53x-C	1.6	1.75	1.9	V
Supply Current	C8051F52x-C/53x-C	—	3	6	µA

Notes:
1. Refer to Section “20. Device Specific Behavior” on page 210.
2. The POR threshold (V_{RST}) is $V_{RST-LOW}$ or V_{RST1}, whichever is higher.
3. The V_{RST}threshold for power fail / brownout is the higher of VDDMON0 and VDDMON1 thresholds, if both are enabled.

Table 3.1. Pin Definitions for the C8051F52x and C8051F52xA (DFN 10) (Continued)

Name	Pin Numbers		Type	Description
	‘F52xA ‘F52x-C	‘F52x		
P0.3/TX*/	—	8	D I/O or A In	Port 0.3. See Port I/O Section for a complete description.
XTAL2			D I/O	External Clock Output. For an external crystal or resonator, this pin is the excitation driver. This pin is the external clock input for CMOS, capacitor, or RC oscillator configurations. See Section “14. Oscillators” on page 135.
P0.2	9	9	D I/O or	Port 0.2. See Port I/O Section for a complete description.
XTAL1			A In	External Clock Input. This pin is the external oscillator return for a crystal or resonator. Section “14. Oscillators” on page 135.
P0.1/	10	10	D I/O or A In	Port 0.1. See Port I/O Section for a complete description.
C2D			D I/O	Bi-directional data signal for the C2 Debug Interface
Note: Please refer to Section “20. Device Specific Behavior” on page 210.				

4.3.5. Output Conversion Code

The registers ADC0H and ADC0L contain the high and low bytes of the output conversion code. When the repeat count is set to 1, conversion codes are represented in 12-bit unsigned integer format and the output conversion code is updated after each conversion. Inputs are measured from 0 to V_{REF} x 4095/4096. Data can be right-justified or left-justified, depending on the setting of the AD0LJST bit (ADC0CN.2). Unused bits in the ADC0H and ADC0L registers are set to 0. Example codes are shown below for both right-justified and left-justified data.

Input Voltage	Right-Justified ADC0H:ADC0L (AD0LJST = 0)	Left-Justified ADC0H:ADC0L (AD0LJST = 1)
V_{REF} x 4095/4096	0x0FFF	0xFFF0
V_{REF} x 2048/4096	0x0800	0x8000
V_{REF} x 2047/4096	0x07FF	0x7FF0
0	0x0000	0x0000

When the ADC0 Repeat Count is greater than 1, the output conversion code represents the accumulated result of the conversions performed and is updated after the last conversion in the series is finished. Sets of 4, 8, or 16 consecutive samples can be accumulated and represented in unsigned integer format. The repeat count can be selected using the AD0RPT bits in the ADC0CF register. The value must be right-justified (AD0LJST = “0”), and unused bits in the ADC0H and ADC0L registers are set to '0'. The following example shows right-justified codes for repeat counts greater than 1. Notice that accumulating 2^n samples is equivalent to left-shifting by *n* bit positions when all samples returned from the ADC have the same value.

Input Voltage	Repeat Count = 4	Repeat Count = 8	Repeat Count = 16
V_{REF} x 4095/4096	0x3FFC	0x7FF8	0xFFF0
V_{REF} x 2048/4096	0x2000	0x4000	0x8000
V_{REF} x 2047/4096	0x1FFC	0x3FF8	0x7FF0
0	0x0000	0x0000	0x0000

SFR Definition 4.5. ADC0CF: ADC0 Configuration

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
AD0SC					AD0RPT		GAINEN	11111000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xBC

Bits7–3: **AD0SC4–0**: ADC0 SAR Conversion Clock Period Bits.
SAR Conversion clock is derived from FCLK by the following equation, where *AD0SC* refers to the 5-bit value held in bits AD0SC4–0. SAR Conversion clock requirements are given in Table 2.3 on page 28.
BURSTEN = 0: FCLK is the current system clock.
BURSTEN = 1: FCLK is the Burst Mode Oscillator, specified in Table 2.3.

$$AD0SC = \frac{FCLK}{CLK_{SAR}} - 1 * \quad \text{or} \quad CLK_{SAR} = \frac{FCLK}{AD0SC + 1}$$

Note: Round the result up.

Bits2–1: **AD0RPT1–0**: ADC0 Repeat Count.
Controls the number of conversions taken and accumulated between ADC0 End of Conversion (ADCINT) and ADC0 Window Comparator (ADCWINT) interrupts. A convert start is required for each conversion unless Burst Mode is enabled. In Burst Mode, a single convert start can initiate multiple self-timed conversions. Results in both modes are accumulated in the ADC0H:ADC0L register. **When AD0RPT1–0 are set to a value other than '00', the AD0LJST bit in the ADC0CN register must be set to '0' (right justified).**
00: 1 conversion is performed.
01: 4 conversions are performed and accumulated.
10: 8 conversions are performed and accumulated.
11: 16 conversions are performed and accumulated.

Bit0: **GAINEN**: Gain Enable Bit.
Controls the gain programming. For more information of the usage, refer to the following chapter: Section “4.4. Selectable Gain” on page 60.

Table 9.2. Special Function Registers

SFRs are listed in alphabetical order. All undefined SFR locations are reserved

Register	Address	Description	Page
ACC	0xE0	Accumulator	89
ADC0CF	0xBC	ADC0 Configuration	65
ADC0CN	0xE8	ADC0 Control	67
ADC0H	0xBE	ADC0	66
ADC0L	0xBD	ADC0	66
ADC0GTH	0xC4	ADC0 Greater-Than Data High Byte	69
ADC0GTL	0xC3	ADC0 Greater-Than Data Low Byte	69
ADC0LTH	0xC6	ADC0 Less-Than Data High Byte	70
ADC0LTL	0xC5	ADC0 Less-Than Data Low Byte	70
ADC0MX	0xBB	ADC0 Channel Select	64
ADC0TK	0xBA	ADC0 Tracking Mode Select	68
B	0xF0	B Register	89
CKCON	0x8E	Clock Control	188
CLKSEL	0xA9	Clock Select	143
CPT0CN	0x9B	Comparator0 Control	78
CPT0MD	0x9D	Comparator0 Mode Selection	80
CPT0MX	0x9F	Comparator0 MUX Selection	79
DPH	0x83	Data Pointer High	87
DPL	0x82	Data Pointer Low	87
EIE1	0xE6	Extended Interrupt Enable 1	102
EIP1	0xF6	Extended Interrupt Priority 1	103
FLKEY	0xB7	Flash Lock and Key	119
IE	0xA8	Interrupt Enable	100
IP	0xB8	Interrupt Priority	101
IT01CF	0xE4	INT0/INT1 Configuration	105
LINADDR	0x92	LIN indirect address pointer	172
LINCF	0x95	LIN master-slave and automatic baud rate selection	173
LINDATA	0x93	LIN indirect data buffer	172
OSCICL	0xB3	Internal Oscillator Calibration	138

12.2. Flash Write and Erase Guidelines

Any system which contains routines which write or erase Flash memory from software involves some risk that the write or erase routines will execute unintentionally if the CPU is operating outside its specified operating range of V_{DD}, system clock frequency, or temperature. This accidental execution of Flash modifying code can result in alteration of Flash memory contents causing a system failure that is only recoverable by re-Flashing the code in the device.

The following guidelines are recommended for any system which contains routines which write or erase Flash from code.

12.2.1. V_{DD} Maintenance and the V_{DD} monitor

1. If the system power supply is subject to voltage or current "spikes," add sufficient transient protection devices to the power supply to ensure that the supply voltages listed in the Absolute Maximum Ratings table are not exceeded.
2. Make certain that the maximum V_{DD} ramp time specification (if applicable) is met. See Section 20.4 on page 211 for more details on V_{DD} ramp time. If the system cannot meet this ramp time specification, then add an external V_{DD} brownout circuit to the $\overline{RST}$ pin of the device that holds the device in reset until V_{DD} reaches the minimum specified V_{DD} and re-asserts $\overline{RST}$ if V_{DD} drops belowthat level. V_{DD} (min) is specified in Table 2.2 on page 26.
3. Enable the on-chip V_{DD} monitor (VDDMON0) and enable it as a reset source as early in code as possible. This should be the first set of instructions executed after the Reset Vector. For C-based systems, this will involve modifying the startup code added by the C compiler. See your compiler documentation for more details. Make certain that there are no delays in software between enabling the V_{DD} monitor (VDDMON0) and enabling it as a reset source. Code examples showing this can be found in “AN201: Writing to Flash from Firmware", available from the Silicon Laboratories web site.
4. As an added precaution, explicitly enable the V_{DD} monitor (VDDMON0) and enable the V_{DD} monitor as a reset source inside the functions that write and erase Flash memory. The V_{DD} monitor enable instructions should be placed just after the instruction to set PSWE to a 1, but before the Flash write or erase operation instruction.
5. Make certain that all writes to the RSTSRC (Reset Sources) register use direct assignment operators and explicitly DO NOT use the bit-wise operators (such as AND or OR). For example, "RSTSRC = 0x02" is correct. "RSTSRC |= 0x02" is incorrect.
6. Make certain that all writes to the RSTSRC register explicitly set the PORSF bit to a 1. Areas to check are initialization code which enables other reset sources, such as the Missing Clock Detector or Comparator, for example, and instructions which force a Software Reset. A global search on "RSTSRC" can quickly verify this.

12.2.2. PSWE Maintenance

1. Reduce the number of places in code where the PSWE bit (PSCTL.0) is set to a 1. There should be exactly one routine in code that sets PSWE to a 1 to write Flash bytes and one routine in code that sets PSWE and PSEE both to a 1 to erase Flash pages.
2. Minimize the number of variable accesses while PSWE is set to a 1. Handle pointer address updates and loop variable maintenance outside the "PSWE = 1;... PSWE = 0;" area. Code examples showing this can be found in “AN201: Writing to Flash from Firmware,” available from the Silicon Laboratories web site.
3. Disable interrupts prior to setting PSWE to a 1 and leave them disabled until after PSWE has been reset to '0'. Any interrupts posted during the Flash write or erase operation will be serviced in priority order after the Flash operation has been completed and interrupts have been re-enabled by software.
4. Make certain that the Flash write and erase pointer variables are not located in XRAM. See your compiler documentation for instructions regarding how to explicitly locate variables in different memory areas.

13. Port Input/Output

Digital and analog resources are available through up to 16 I/O pins. Port pins are organized as two or one byte-wide Ports. Each of the Port pins can be defined as general-purpose I/O (GPIO) or analog input/output; Port pins P0.0 - P2.7 can be assigned to one of the internal digital resources as shown in Figure 13.3. The designer has complete control over which functions are assigned, limited only by the number of physical I/O pins. This resource assignment flexibility is achieved through the use of a Priority Crossbar Decoder. Note that the state of a Port I/O pin can always be read in the corresponding Port latch, regardless of the Crossbar settings.

The Crossbar assigns the selected internal digital resources to the I/O pins based on the peripheral priority order of the Priority Decoder (Figure 13.3 and Figure 13.4). The registers XBR0 and XBR1, defined in SFR Definition 13.1 and SFR Definition 13.2, are used to select internal digital functions.

Port I/O pins are 5.25 V tolerant over the operating range of V_{REGIN}. Figure 13.2 shows the Port cell circuit. The Port I/O cells are configured as either push-pull or open-drain in the Port Output Mode registers (PnMDOUT, where n = 0,1). Complete Electrical Specifications for Port I/O are given in Table 2.10 on page 33.

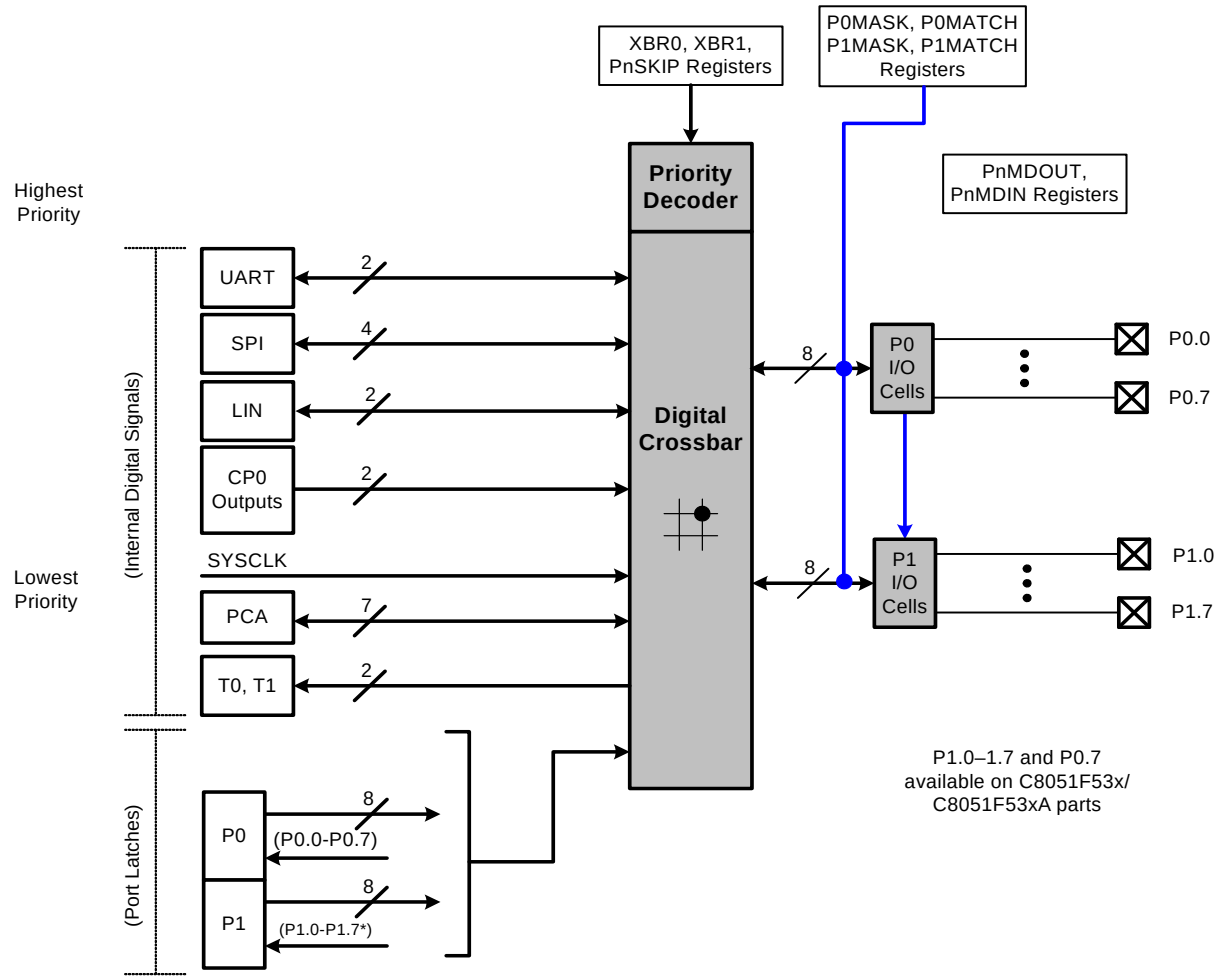

Figure 13.1. Port I/O Functional Block Diagram

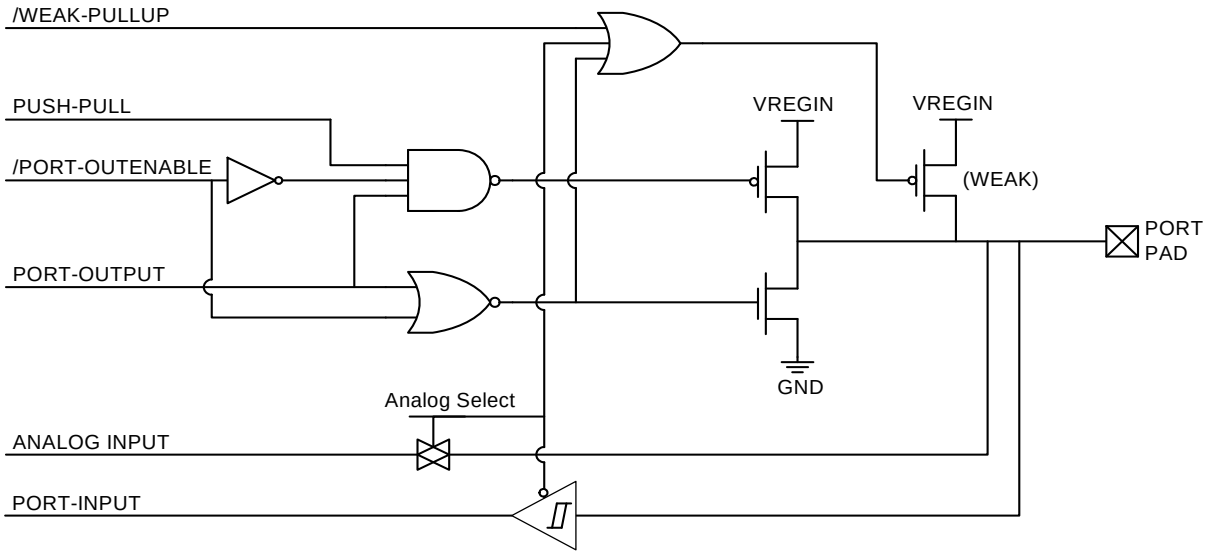

Figure 13.2. Port I/O Cell Block Diagram

SFR Definition 13.2. XBR1: Port I/O Crossbar Register 1

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
WEAKPUD	XBARE	T1E	T0E	ECIE	Reserved	PCA0ME		00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	

SFR Address: 0xE2

Bit7: **WEAKPUD**: Port I/O Weak Pullup Disable.
0: Weak Pullups enabled (except for Ports whose I/O are configured as analog input).
1: Weak Pullups disabled.
Bit6: **XBARE**: Crossbar Enable.
0: Crossbar disabled.
1: Crossbar enabled.
Bit5: **T1E**: T1 Enable
0: T1 unavailable at Port pin.
1: T1 routed to Port pin.
Bit4: **T0E**: T0 Enable
0: T0 unavailable at Port pin.
1: T0 routed to Port pin.
Bit3: **ECIE**: PCA0 External Counter Input Enable
0: ECI unavailable at Port pin.
1: ECI routed to Port pin.
Bit2: **Reserved**. Must Write 0b.
Bits1–0: **PCA0ME**: PCA Module I/O Enable Bits.
00: All PCA I/O unavailable at Port pins.
01: CEX0 routed to Port pin.
10: CEX0, CEX1 routed to Port pins.
11: CEX0, CEX1, CEX2 routed to Port pins.

13.3. General Purpose Port I/O

Port pins that remain unassigned by the Crossbar and are not used by analog peripherals can be used for general purpose I/O. Ports P0–P1 are accessed through corresponding special function registers (SFRs) that are both byte addressable and bit addressable. When writing to a Port, the value written to the SFR is latched to maintain the output data value at each pin. When reading, the logic levels of the Port's input pins are returned regardless of the XBRn settings (i.e., even when the pin is assigned to another signal by the Crossbar, the Port register can always read its corresponding Port I/O pin). The exception to this is the execution of the read-modify-write instructions that target a Port Latch register as the destination. The read-modify-write instructions when operating on a Port SFR are the following: ANL, ORL, XRL, JBC, CPL, INC, DEC, DJNZ and MOV, CLR or SETB, when the destination is an individual bit in a Port SFR. For these instructions, the value of the latch register (not the pin) is read, modified, and written back to the SFR.

SFR Definition 14.1. OSCICN: Internal Oscillator Control

R/W	R/W	R/W	R	R	R/W	R/W	R/W	Reset Value
IOSCEN1	IOSCEN0	SUSPEND	IFRDY	—	IFCN2	IFCN1	IFCN0	11000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	

SFR Address: 0xB2

Bits7–6: **IOSCEN[1:0]**: Internal Oscillator Enable Bits.
00: Oscillator Disabled.
01: Reserved.
10: Reserved.
11: Oscillator Enabled in Normal Mode and Disabled in Suspend Mode.

Bit5: **SUSPEND**: Internal Oscillator Suspend Enable Bit.
Setting this bit to logic 1 places the internal oscillator in SUSPEND mode. The internal oscillator resumes operation when one of the SUSPEND mode awakening events occur.

Bit4: **IFRDY**: Internal Oscillator Frequency Ready Flag.
0: Internal Oscillator is not running at programmed frequency.
1: Internal Oscillator is running at programmed frequency.

Bit3: **UNUSED**. Read = 0b, Write = don't care.

Bits2–0: **IFCN2–0**: Internal Oscillator Frequency Control Bits.
000: SYSCLK derived from Internal Oscillator divided by 128 (default).
001: SYSCLK derived from Internal Oscillator divided by 64.
010: SYSCLK derived from Internal Oscillator divided by 32.
011: SYSCLK derived from Internal Oscillator divided by 16.
100: SYSCLK derived from Internal Oscillator divided by 8.
101: SYSCLK derived from Internal Oscillator divided by 4.
110: SYSCLK derived from Internal Oscillator divided by 2.
111: SYSCLK derived from Internal Oscillator divided by 1.

SFR Definition 14.4. OSCXCN: External Oscillator Control

R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
XTLVLD	XOSCMD2	XOSCMD1	XOSCMD0	Reserved	XFCN2	XFCN1	XFCN0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
							SFR Address:	0xB1

Bit7: **XTLVLD**: Crystal Oscillator Valid Flag. (Read only when XOSCMD = 11x.)
0: Crystal Oscillator is unused or not yet stable.
1: Crystal Oscillator is running and stable.

Bits6–4: **XOSCMD2–0**: External Oscillator Mode Bits.
00x: External Oscillator circuit off.
010: External CMOS Clock Mode.
011: External CMOS Clock Mode with divide by 2 stage.
100: RC Oscillator Mode.
101: Capacitor Oscillator Mode.
110: Crystal Oscillator Mode.
111: Crystal Oscillator Mode with divide by 2 stage.

Bit3: **RESERVED**. Read = 0b; Must write 0b.

Bits2–0: **XFCN2–0**: External Oscillator Frequency Control Bits.
000-111: See table below:

XFCN	Crystal (XOSCMD = 11x)	RC (XOSCMD = 10x)	C (XOSCMD = 10x)
000	f ≤ 20 kHz	f ≤ 25 kHz	K Factor = 0.87
001	20 kHz < f ≤ 58 kHz	25 kHz < f ≤ 50 kHz	K Factor = 2.6
010	58 kHz < f ≤ 155 kHz	50 kHz < f ≤ 100 kHz	K Factor = 7.7
011	155 kHz < f ≤ 415 kHz	100 kHz < f ≤ 200 kHz	K Factor = 22
100	415 kHz < f ≤ 1.1 MHz	200 kHz < f ≤ 400 kHz	K Factor = 65
101	1.1 MHz < f ≤ 3.1 MHz	400 kHz < f ≤ 800 kHz	K Factor = 180
110	3.1 MHz < f ≤ 8.2 MHz	800 kHz < f ≤ 1.6 MHz	K Factor = 664
111	8.2 MHz < f ≤ 25 MHz	1.6 MHz < f ≤ 3.2 MHz	K Factor = 1590

Crystal Mode (Circuit from Figure 14.1, Option 1; XOSCMD = 11x)
Choose XFCN value to match crystal or resonator frequency.

RC Mode (Circuit from Figure 14.1, Option 2; XOSCMD = 10x)
Choose XFCN value to match frequency range:
$f = 1.23(10^3) / (R \times C)$, where
f = frequency of clock in MHz
C = capacitor value in pF
R = Pullup resistor value in kΩ

C Mode (Circuit from Figure 14.1, Option 3; XOSCMD = 10x)
Choose K Factor (KF) for the oscillation frequency desired:
$f = KF / (C \times V_{DD})$, where
f = frequency of clock in MHz
C = capacitor value the XTAL2 pin in pF
V_{DD} = Power Supply on MCU in volts

15.2. Operational Modes

UART0 provides standard asynchronous, full duplex communication. The UART mode (8-bit or 9-bit) is selected by the S0MODE bit (SCON0.7). Typical UART connection options are shown below.

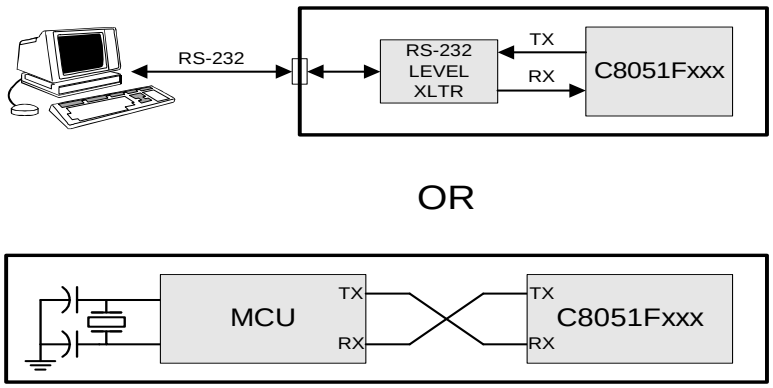

Figure 15.3. UART Interconnect Diagram

15.2.1. 8-Bit UART

8-Bit UART mode uses a total of 10 bits per data byte: one start bit, eight data bits (LSB first), and one stop bit. Data are transmitted LSB first from the TX0 pin and received at the RX0 pin. On receive, the eight data bits are stored in SBUF0 and the stop bit goes into RB80 (SCON0.2).

Data transmission begins when software writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to logic 1. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: RI0 must be logic 0, and if MCE0 is logic 1, the stop bit must be logic 1. In the event of a receive data overrun, the first received 8 bits are latched into the SBUF0 receive register and the following overrun data bits are lost.

If these conditions are met, the eight bits of data is stored in SBUF0, the stop bit is stored in RB80 and the RI0 flag is set. If these conditions are not met, SBUF0 and RB80 will not be loaded and the RI0 flag will not be set. An interrupt will occur if enabled when either TI0 or RI0 is set.

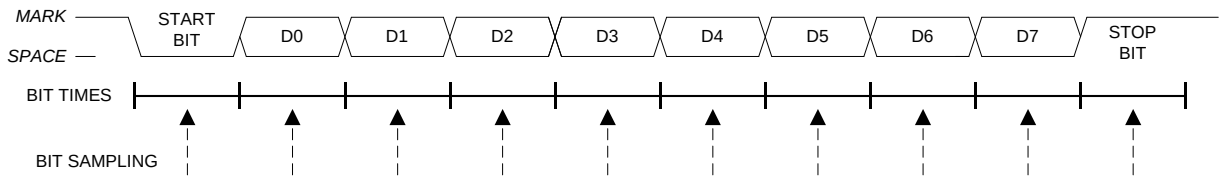

Figure 15.4. 8-Bit UART Timing Diagram

The shift register contents are locked after the slave detects the first edge of SCK. Writes to SPI0DAT that occur after the first SCK edge will be held in the TX latch until the end of the current transfer.

When configured as a slave, SPI0 can be configured for 4-wire or 3-wire operation. The default, 4-wire slave mode, is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 1. In 4-wire mode, the NSS signal is routed to a port pin and configured as a digital input. SPI0 is enabled when NSS is logic 0, and disabled when NSS is logic 1. The bit counter is reset on a falling edge of NSS. Note that the NSS signal must be driven low at least 2 system clocks before the first active edge of SCK for each byte transfer. Figure 16.4 shows a connection diagram between two slave devices in 4-wire slave mode and a master device.

3-wire slave mode is active when NSSMD1 (SPI0CN.3) = 0 and NSSMD0 (SPI0CN.2) = 0. NSS is not used in this mode, and is not mapped to an external port pin through the crossbar. Since there is not a way of uniquely addressing the device in 3-wire slave mode, SPI0 must be the only slave device present on the bus. It is important to note that in 3-wire slave mode there is no external means of resetting the bit counter that determines when a full byte has been received. The bit counter can only be reset by disabling and re-enabling SPI0 with the SPIEN bit. Figure 16.3 shows a connection diagram between a slave device in 3-wire slave mode and a master device.

16.4. SPI0 Interrupt Sources

When SPI0 interrupts are enabled, the following four flags will generate an interrupt when they are set to logic 1:

Note that all of the following interrupt bits must be cleared by software.

1. The SPI Interrupt Flag, SPIF (SPI0CN.7) is set to logic 1 at the end of each byte transfer. This flag can occur in all SPI0 modes.
2. The Write Collision Flag, WCOL (SPI0CN.6) is set to logic 1 if a write to SPI0DAT is attempted when the transmit buffer has not been emptied to the SPI shift register. When this occurs, the write to SPI0DAT will be ignored, and the transmit buffer will not be written.This flag can occur in all SPI0 modes.
3. The Mode Fault Flag MODF (SPI0CN.5) is set to logic 1 when SPI0 is configured as a master in multi-master mode and the NSS pin is pulled low. When a Mode Fault occurs, the MSTEN and SPIEN bits in SPI0CN are set to logic 0 to disable SPI0 and allow another master device to access the bus.
4. The Receive Overrun Flag RXOVRN (SPI0CN.4) is set to logic 1 when configured as a slave, and a transfer is completed while the receive buffer still holds an unread byte from a previous transfer. The new byte is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte which caused the overrun is lost.

SFR Definition 16.3. SPI0CKR: SPI0 Clock Rate

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
SCR7	SCR6	SCR5	SCR4	SCR3	SCR2	SCR1	SCR0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	

SFR Address: 0xA2

Bits7–0: **SCR7–SCR0**: SPI0 Clock Rate.
These bits determine the frequency of the SCK output when the SPI0 module is configured for master mode operation. The SCK clock frequency is a divided version of the system clock, and is given in the following equation, where *SYSCLK* is the system clock frequency and *SPI0CKR* is the 8-bit value held in the SPI0CKR register.

$$f_{SCK} = \frac{SYSCLK}{2 \times (SPI0CKR + 1)}$$

for 0 <= SPI0CKR <= 255

Example: If SYSCLK = 2 MHz and SPI0CKR = 0x04,

$$f_{SCK} = \frac{2000000}{2 \times (4 + 1)}$$

$$f_{SCK} = 200kHz$$

17. LIN (C8051F520/0A/3/3A/6/6A and C8051F530/0A/3/3A/6/6A)

Important Note: This chapter assumes an understanding of the Local Interconnect Network (LIN) protocol. For more information about the LIN protocol, including specifications, please refer to the LIN consortium (http://www.lin-subbus.org/).

LIN is an asynchronous, serial communications interface used primarily in automotive networks. The Silicon Laboratories LIN controller is compliant to the 2.1 Specification, implements a complete hardware LIN interface, and includes the following features:

- Selectable Master and Slave modes.
- Automatic baud rate option in slave mode
- The internal oscillator is accurate to within 0.5% of 24.5 MHz across the entire temperature range and for VDD voltages greater than or equal to the minimum output of the on-chip voltage regulator, so an external oscillator is not necessary for master mode operation for most systems.

Note: The minimum system clock (SYSCLK) required when using the LIN peripheral is 8 MHz.

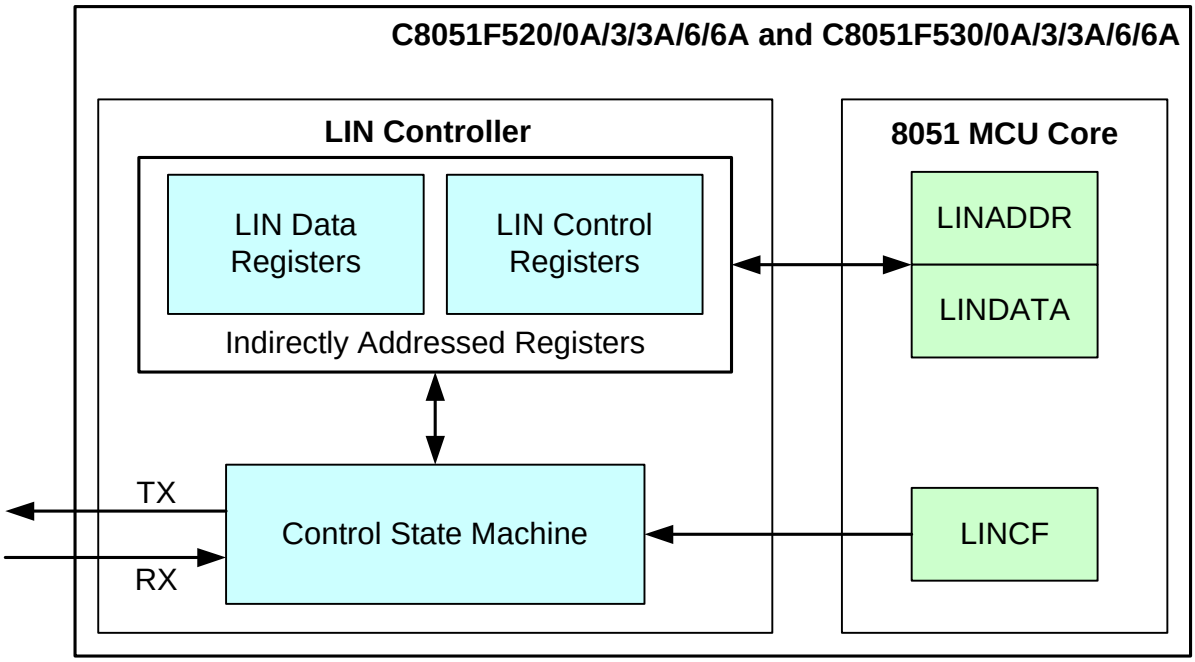

Figure 17.1. LIN Block Diagram

The LIN peripheral has four main components:

1. LIN Access Registers—Provide the interface between the MCU core and the LIN peripheral.
2. LIN Data Registers—Where transmitted and received message data bytes are stored.
3. LIN Control Registers—Control the functionality of the LIN interface.
4. Control State Machine and Bit Streaming Logic—Contains the hardware that serializes messages and controls the bus timing of the controller.

17.4. LIN Slave Mode Operation

When the device is configured for slave mode operation, it must wait for a command from a master node. Access from the firmware to data buffer and ID registers of the LIN peripheral is only possible when a data request is pending (DTREQ bit (LIN0ST.4) is 1) and also when the LIN bus is not active (ACTIVE bit (LIN0ST.7) is set to 0).

The LIN peripheral in slave mode detects the header of the message frame sent by the LIN master. If slave synchronization is enabled (autobaud), the slave synchronizes its internal bit time to the master bit time.

The LIN peripheral configured for slave mode will generated an interrupt in one of three situations:

1. After the reception of the IDENTIFIER FIELD.
2. When an error is detected.
3. When the message transfer is completed.

The application should perform the following steps when an interrupt is detected:

1. Check the status of the DTREQ bit (LIN0ST.4). This bit is set when the IDENTIFIER FIELD has been received.
2. If DTREQ (LIN0ST.4) is set, read the identifier from LIN0ID and process it. If DTREQ (LIN0ST.4) is not set, continue to step 7.
3. Set the TXRX bit (LIN0CTRL.5) to 1 if the current frame is a transmit operation for the slave and set to 0 if the current frame is a receive operation for the slave.
4. Load the data length into LIN0SIZE.
5. For a slave transmit operation, load the data to transmit into the data buffer.
6. Set the DTACK bit (LIN0CTRL.4). Continue to step 10.
7. If DTREQ (LIN0ST.4) is not set, check the DONE bit (LIN0ST.0). The transmission was successful if the DONE bit is set.
8. If the transmission was successful and the current frame was a receive operation for the slave, load the received data bytes from the data buffer.
9. If the transmission was not successful, check LIN0ERR to determine the nature of the error. Further error handling has to be done by the application.
10. Set the RSTINT (LIN0CTRL.3) and RSTERR bits (LIN0CTRL.2) to reset the interrupt request and the error flags.

In addition to these steps, the application should be aware of the following:

1. If the current frame is a transmit operation for the slave, steps 1 through 5 must be completed during the IN-FRAME RESPONSE SPACE. If it is not completed in time, a timeout will be detected by the master.
2. If the current frame is a receive operation for the slave, steps 1 through 5 have to be finished until the reception of the first byte after the IDENTIFIER FIELD. Otherwise, the internal receive buffer of the LIN peripheral will be overwritten and a timeout error will be detected in the LIN peripheral.
3. The LIN module does not directly support LIN Version 1.3 Extended Frames. If the application detects an unknown identifier (e.g. extended identifier), it has to write a 1 to the STOP bit (LIN0CTRL.7) instead of setting the DTACK (LIN0CTRL.4) bit. At that time, steps 2 through 5 can then be skipped. In this situation, the LIN peripheral stops the processing of the LIN communication until the next SYNC BREAK is received.
4. Changing the configuration of the checksum during a transaction will cause the interface to reset and the transaction to be lost. To prevent this, the checksum should not be configured while a transaction is

19.2.2. Software Timer (Compare) Mode

In Software Timer mode, the PCA counter/timer value is compared to the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn). When a match occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1 and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. Setting the ECOMn and MATn bits in the PCA0CPMn register enables Software Timer mode.

Important Note About Capture/Compare Registers: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to 0; writing to PCA0CPHn sets ECOMn to 1.

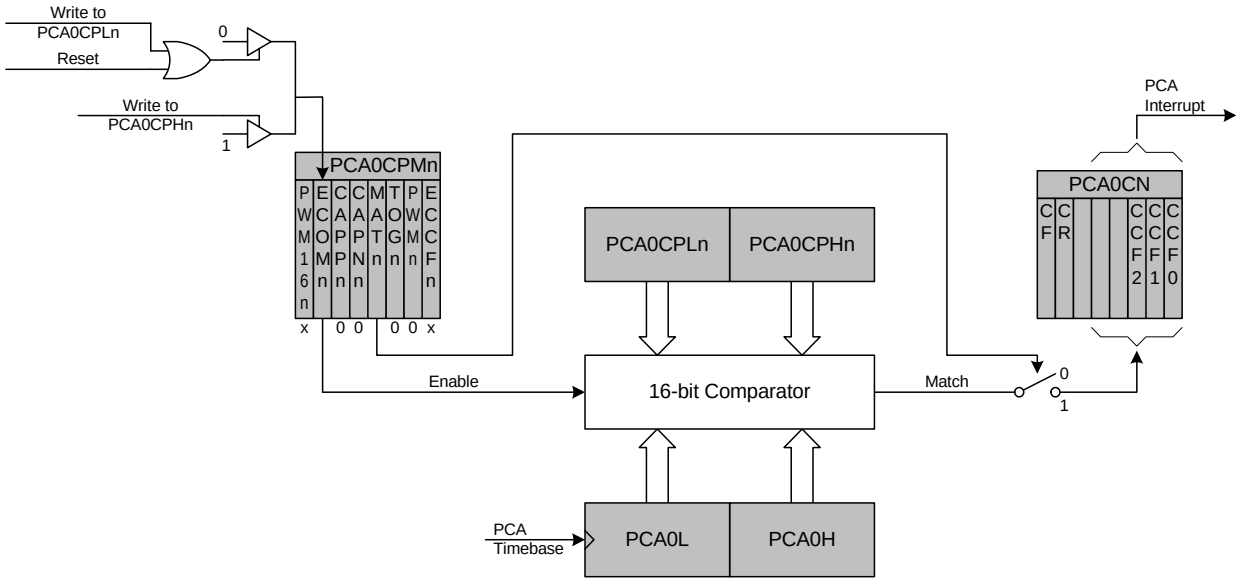

Figure 19.5. PCA Software Timer Mode Diagram

21.2. C2 Pin Sharing

The C2 protocol allows the C2 pins to be shared with user functions so that in-system debugging and Flash programming functions may be performed. This is possible because C2 communication is typically performed when the device is in the halt state, where all on-chip peripherals and user software are stalled. In this halted state, the C2 interface can safely ‘borrow’ the C2CK (/RST) and C2D (P0.1 or P0.6) pins. In most applications, external resistors are required to isolate C2 interface traffic from the user application. A typical isolation configuration is shown in Figure 21.1.

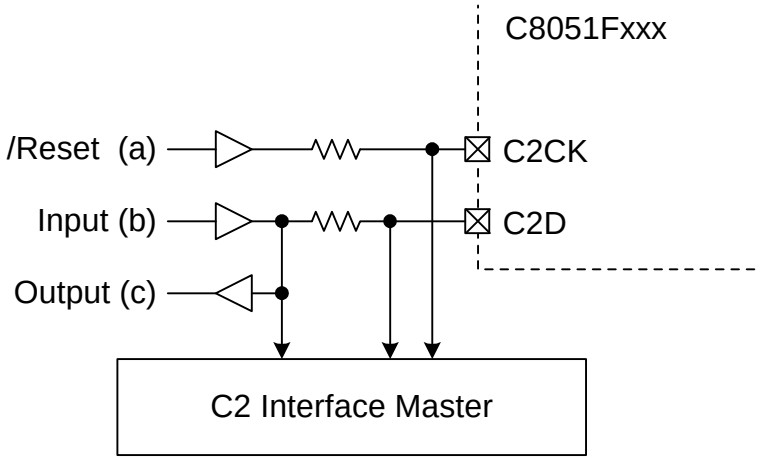

Figure 21.1. Typical C2 Pin Sharing

The configuration in Figure 21.1 assumes the following:

1. The user input (b) cannot change state while the target device is halted.
2. The /RST pin on the target device is used as an input only.

Additional resistors may be necessary depending on the specific application.

Revision 1.2 to 1.3

- Updated “System Overview” on page 13 with a voltage range specification for the internal oscillator.
- Updated Table 2.11 on page 34 with new conditions for the internal oscillator accuracy. The internal oscillator accuracy is dependent on the operating voltage range.
- Updated Section 2 to remove the internal oscillator curve across temperature diagram.
- Updated Figure “4.5 12-Bit ADC Burst Mode Example with Repeat Count Set to 4” on page 58 with new timing diagram when using CNVSTR pin.
- Updated SFR Definition 5.1 (REF0CN) with oscillator suspend requirement for ZTCEN.
- Updated SFR Definition 6.1 (REG0CN) with a new definition for Bit 6. The bit 6 reset value is 1b and must be written to 1b.
- Updated Section “8.3.3. Suspend Mode” on page 90 with note regarding ZTCEN.
- Updated Section “17. LIN (C8051F520/0A/3/3A/6/6A and C8051F530/0A/3/3A/6/6A)” on page 164 with a voltage range specification for the internal oscillator.

Revision 1.3 to 1.4

- Added ‘AEC-Q100’ qualification information on page 1.
- Changed page headers throughout the document from ‘C8051F52x/F52xA/F53x/F53xA’ to ‘C8051F52x/53x’.
- Updated supply voltage to "2.0 to 5.25 V" on page 1 and in Section 1 on page 13.
- Corrected reference to development kit (C8051F530DK) in Section “1.2.4. On-Chip Debug Circuitry” on page 18.
- Updated minimum Supply Input Voltage (V_{REGIN}) for C8051F52x-C/F53x-C devices in Table 2.2 on page 26 and Table 2.6 on page 30.
- Updated digital supply current (I_{DD} and Idle I_{DD}) typical values for condition ‘Clock = 25 MHz’ in Table 2.2 on page 26.
- Updated I_{DD} Frequency Sensitivity and Idle I_{DD} Frequency Sensitivity values in Table 2.2 on page 26; removed Figure 2.1 and Figure 2.2 that used to provide the same frequency sensitivity slopes. Also removed IDD Supply Sensitivity and Idle IDD Supply Sensitivity typical values.
- Added Digital Supply Current (Stop or Suspend Mode) values at multiple temperatures Table 2.2 on page 26.
- Added a note in Table 2.3, “ADC0 Electrical Characteristics,” on page 28 with reference to Section “4.4. Selectable Gain” on page 60; also added note to indicate that additional tracking time may be necessary if VDD is less than the minimum specified VDD.
- Split off temperature sensor specifications from Table 2.3 into a separate table Table 2.4; Updated temperature sensor gain and added supply current values.
- Added temperature condition for Bias Current specification in Table 2.6 on page 30.
- Updated Comparator Input Offset Voltage values in Table 2.7 on page 31.
- Updated VDD Monitor (VDDMON0) Low Threshold ($V_{RST-LOW}$) minimum value for C8051F52xA/F52x-C/F53xA/F53x-C devices in Table 2.8 on page 32.
- Updated VDD Monitor (VDDMON0) supply current values in Table 2.8 on page 32.
- Added specifications for the new level-sensitive VDD monitor (VDDMON1) to Table 2.8, “Reset Electrical Characteristics,” on page 32 and also added notes to clarify the applicable V_{RST} theshold level.
- Added note in Table 2.9, “Flash Electrical Characteristics,” on page 33 to describe the minimum flash programming temperature for –I (Industrial Grade) devices; Also added the same note and references to it in Section “12.1. Programming The Flash Memory” on page 113, Section “12.3. Non-volatile Data Storage” on page 117, and in SFR Definition 12.1 (PSCTL).

- Replaced minimum VDD value for Flash write/erase operations in Table 2.9 on page 33 with references to the $V_{RST-HIGH}$ theshold specified in Table 2.8 on page 32.
- Removed Output Low Voltage values for condition 'V_{REGIN} = 1.8 V' from Table 2.10, "Port I/O DC Electrical Characteristics," on page 33.
- Corrected minor typo ("IFCN = 111b") in Table 2.11, "Internal Oscillator Electrical Characteristics," on page 34.
- Removed the typical value and added the maximum value for the 'Wake-up Time From Suspend' specification with the 'ZTCEN = 0' condition in Table 2.11, "Internal Oscillator Electrical Characteristics," on page 34.
- Added Internal Oscillator Supply current values at specific temperatures for conditions 'ZTCEN = 1' and 'ZTCEN = 0' in Table 2.11, "Internal Oscillator Electrical Characteristics," on page 34. Also updated the table name to clarify that the specifications apply to the internal oscillator.
- Updated Section "1.1. Ordering Information" on page 14 and Table 1.1 with new C8051F52x-C/F53x-C part numbers.
- Updated Table 1.2, "Product Selection Guide (Not Recommended for New Designs)," on page 15 to include C8051F52xA/F53xA part numbers.
- Updated Figure 1.1, Figure 1.2, Figure 1.3, and Figure 1.4 titles to clarify applicable silicon revisions.
- Added figure references to pinout diagrams (Figure 3.1, Figure 3.4, and Figure 3.7) and updated labels to clarify applicable part numbers.
- Updated Table 3.1, Table 3.4, and Table 3.7 to indicate pinouts applicable to C8051F52x-C/F53x-C devices.
- Added note in Section "6. Voltage Regulator (REG0)" on page 74 to indicate the need for bypass capacitors for voltage regulator stability.
- Updated Figure 11.1 on Page 106 and text in Section "11.1. Power-On Reset" on page 107 and Section "11.2. Power-Fail Reset / VDD Monitors (VDDMON0 and VDDMON1)" on page 108 to describe the new level-sensitive V_{DD} monitor (VDDMON1).
- Updated SFR Definition 11.1. "VDDMON: VDD Monitor Control" on page 109 to include the VDM1EN bit (bit 4) that controls the new level-sensitive V_{DD} monitor (VDDMON1).
- Added notes in Section 11.1 on page 107, Section 11.2 on page 108, and Section 11.3 on page 110 with references to relevant parts of Section "20. Device Specific Behavior" on page 210.
- Moved some notes related to VDD Monitor (VDDMON0) High Threshold setting ($V_{RST-HIGH}$) from Section 11.2 on page 108 to Section 20.5 on page 212 in Section "20. Device Specific Behavior".
- Added Section "11.2.1. VDD Monitor Thresholds and Minimum VDD" on page 108 to describe the recommendations for minimum V_{DD} as it relates to the V_{DD} monitor thresholds.
- Clarified text in Section "11.7. Flash Error Reset" on page 110.
- Clarified text in items 2, 3 and 4 in Section "12.2.1. V_{DD} Maintenance and the V_{DD} monitor" on page 115 to reference appropriate specification tables and specify "VDDMON0".